

DESCRIPTION

The VX3321 receiver converts the four LVDS data streams back into 28 bits of CMOS/TTL data .

This chipset is the ideal solution to resolve EMI and cable size problems associated with high speed TTL interfaces.

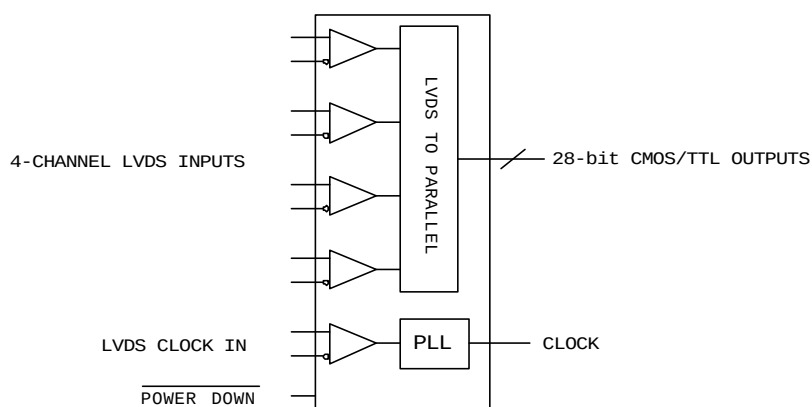
ABSOLUTE MAXIMUM RATINGS

■ Supply voltage	-0.3V to +4V
■ CMOS/TTL input voltage	-0.3V to ($V_{DD}+0.3V$)
■ CMOS/TTL output voltage	-0.3V to ($V_{DD}+0.3V$)
■ LVDS receiver input voltage	-0.3V to ($V_{DD}+0.3V$)
■ LVDS output short circuit duration	continuous
■ Junction temperature	+150°C
■ Storage temperature range	-65°C to +150°C
■ Lead temperature(Soldering 4sec)	+260°C

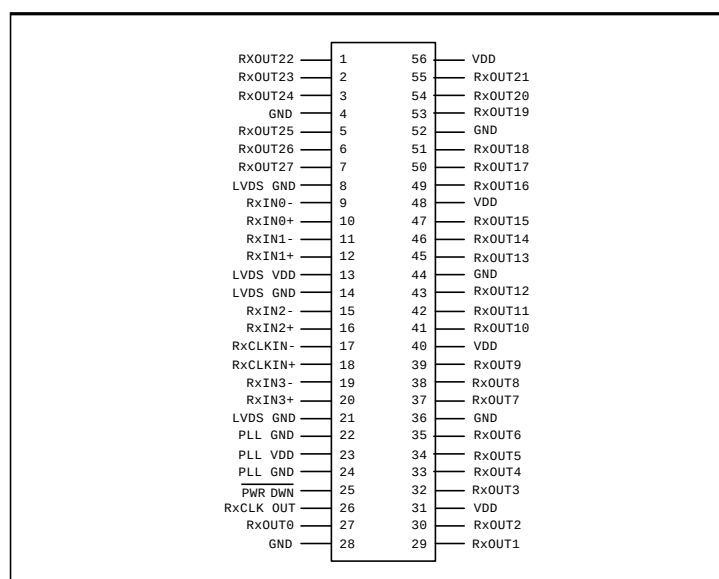
FEATURES

- Supply voltage 3.0~3.6V
- 20 to 85 MHz input clock support
- 50% duty cycle on receiver output clock
- Power-down mode < 198uW (max.)
- Narrow bus reduces cable size and cost
- +/- 1V common mode range (around + 1.2V)
- PLL requires no external components
- Rising edge data strobe
- TSSOP-56

FUNCTION BLOCK DIAGRAM



PINS DIAGRAM



RECOMMENDED OPERATING CONDITIONS

	Min	Nom	Max	Unit
Supply voltage(V_{DD})	3.0	3.3	3.6	V
Operating free air temperature(T_A)	-10	+25	+70	°C
Receiver input range	0		2.4	V

CMOS/TTL CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{IH}	High level input voltage		2.0		V_{DD}	V
V_{IL}	Low level input voltage		GND		0.8	V
V_{OH}	High level output voltage	$I_{OH}=-0.4mA$	2.7	3.3		V
V_{OL}	Low level output voltage	$I_{OL}=2mA$		0.06	0.3	V
I_{IN}	Input current	$V_{IN}=GND$ or V_{DD}		± 5.1	± 10	μA
I_{OS}	Short circuit output current	$V_{OUT}=0V$		-60	-120	mA

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{TH}	Differential input high threshold	$V_{OS}=+1.2V$			+100	mV
V_{TL}	Differential input low threshold		-100			mV
I_{IN}	Input current	$V_{IN}=+2.4V; V_{DD}=3.6V$			± 10	μA
		$V_{IN}=0V; V_{DD}=3.6V$			± 10	μA
I_{DDRW}	Supply current worst case	$C_L=8pF$; Worst case pattern @85MHz (Fig.1, Fig.2)		96	135	mA
I_{DDRZ}	Supply current power down mode	$\overline{PWRDWN}=0V$		10	55	μA

Note1: Typical values are given for $V_{DD}=3.3V$ and $T_A=+25^\circ C$

TIMING CHARACTERISTICS

Symbol	Parameter		Min	Typ	Max	Unit
CLHT	CMOS/TTL low to high transition time (Fig.2)			2	3.5	nS
CHLT	CMOS/TTL high to low transition time (Fig.2)			2	3.5	nS
RSP _{os} 0	Receiver input strobe position for bit0	85MHz (Fig.7)	0.54	0.84	1.14	nS
RSP _{os} 1	Receiver input strobe position for bit1		2.22	2.52	2.82	nS
RSP _{os} 2	Receiver input strobe position for bit2		3.9	4.2	4.5	nS
RSP _{os} 3	Receiver input strobe position for bit3		5.58	5.88	6.18	nS
RSP _{os} 4	Receiver input strobe position for bit4		7.26	7.56	7.86	nS
RSP _{os} 5	Receiver input strobe position for bit5		8.94	9.24	9.54	nS
RSP _{os} 6	Receiver input strobe position for bit6		10.62	10.92	11.22	nS
RCOP	RxCLK OUT period (Fig.3)		11.76	T	50	nS
RCOH	RxCLK OUT high time (Fig.3)	85MHz (Fig.7)	3.7	5	6.3	nS
RCOL	RxCLK OUT low time (Fig.3)		3.7	5	6.3	nS
RSKM	RxIN skew margin (note1) (Fig.8)		340			pS
RSRC	RxOUT setup to RxCLK OUT (Fig.3)		4			nS
RHRC	RxOUT hold to RxCLK OUT (Fig.3)		4			nS
RCCD	RxCLK IN to RxCLK OUT delay (note1) (Fig.6)		3.4	5	7.3	nS
RPLLS	Phase lock loop set (Fig.5)				10	mS
RPDD	Power down delay (Fig.4)				1	uS

Note1: The values are given for $V_{DD}=3.3V$ and $T_A=+25^{\circ}C$

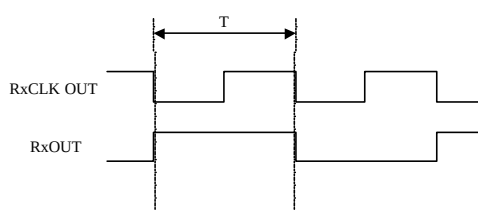
TIMING DIAGRAMS


Figure 1. "Worst Case" Test Pattern



Figure 2. Receiver CMOS/TTL Output Load and Transition Times

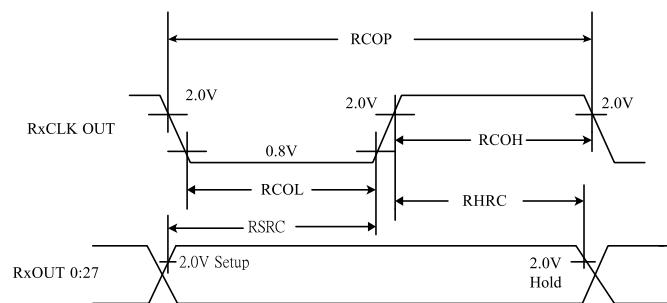


Figure 3. Receiver Setup/Hold and High/Low Times

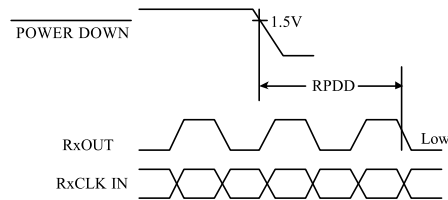


Figure 4. Rx Powerdown Delay

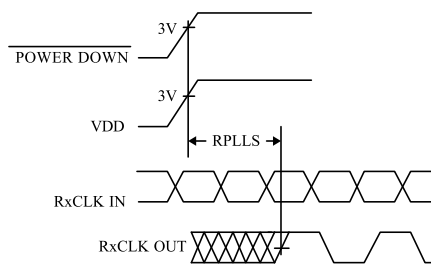


Figure 5. Rx PLL Set Time

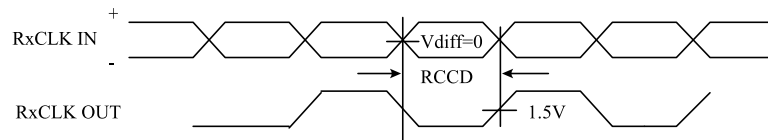


Figure 6. (Receiver) Clock IN to Clock Out Delay

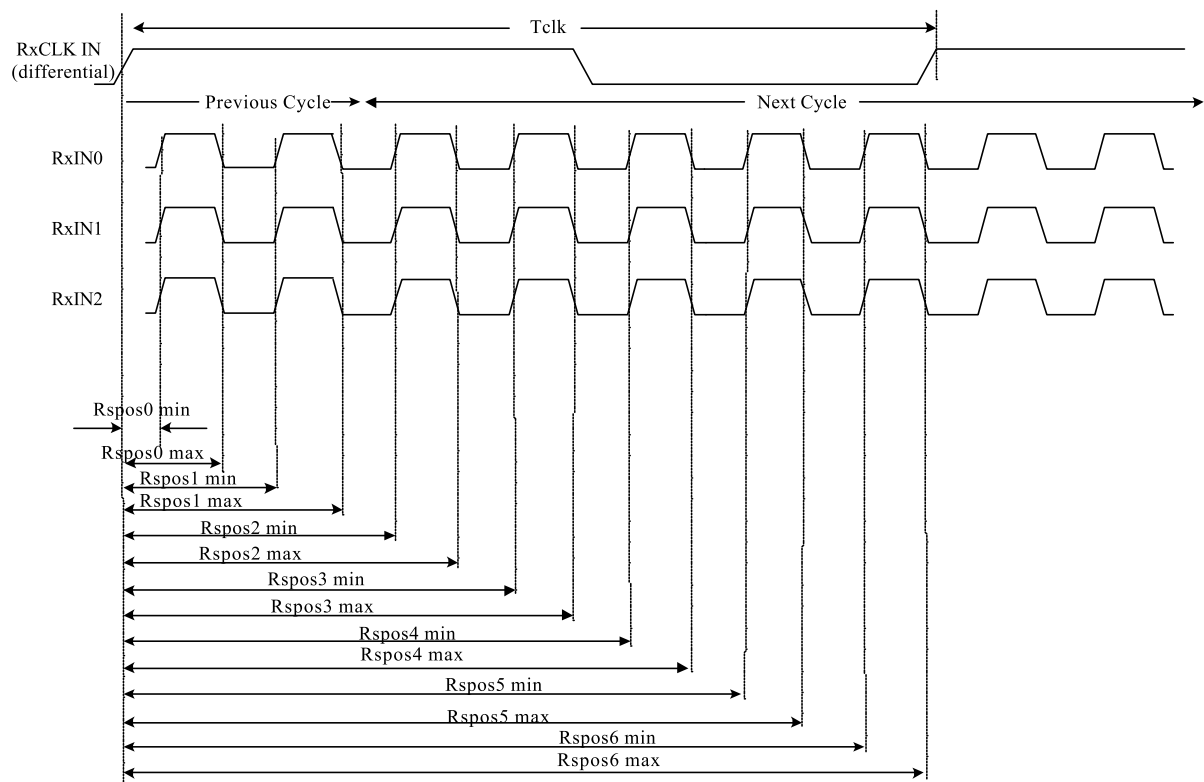


Figure 7. Receiver LVDS input Strobe Position

- C-Setup and Hold Time(Internal data Sampling Window) defined by R_{spos} (receiver input strobe position) min and max
- T_{ppos} -Transmitter output pulse position (min and max)
- RSKM Cable Skew(type,length) +Source Clock Jitter (cycle to cycle)+ISI(inter-symbol interference)
- Cable skew-typically 10 ps-40 ps per foot, media dependent

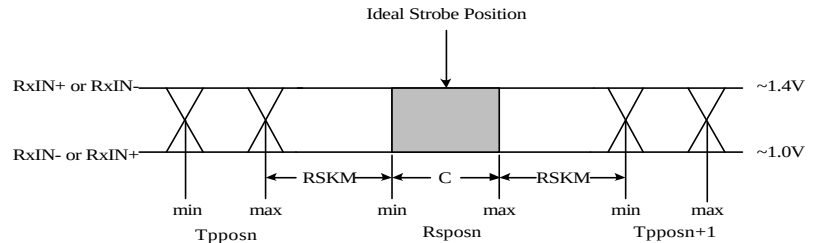


Figure8. Receiver LVDS Input Skew Margin

PIN DESCRIPTION

Pin Name	I/O	No.	Description
RxIN+	I	4	Positive LVDS differential data inputs.
RxIN-	I	4	Negative LVDS differential data inputs.
RxOUT	O	28	TTL level data outputs.
RxCLK IN+	I	1	Positive LVDS differential clock inputs.
RxCLK IN-	I	1	Negative LVDS differential clock inputs.
RxCLK OUT	O	1	TTL level clock output. The rising edge acts as data strobe.
PWRDWN	I	1	TTL level input. When asserted(low input)the receiver outputs are low.
Vdd	I	4	Power supply pins for TTL outputs.
GND	I	5	Ground pins for TTL outputs.
PLL Vdd	I	1	Power supply for PLL.
PLL GND	I	2	Ground pin for PLL.
LVDS Vdd	I	1	Power supply pin for LVDS inputs.
LVDS GND	I	3	Ground pins for LVDS inputs.

Physical Dimensions inches (millimeters) unless otherwise noted